



Printed Circuit Boards
Interconnection Carriers

PRINTED CIRCUIT BOARDS

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 243 FR4 105 L36.105 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_243_FR4_105_L36.105_p18

Layers	in μ	Material	Build-Up	Assembly				
Layer-1	105 μ	Copper	(180 μ PrePreg-Type: 7628)	A1				
	180 μ	Prepreg						
Layer-2	180 μ	Prepreg			A2			
	105 μ	Copper						
Layer-3	360 μ	L-FR4				B		
	105 μ	Copper						
Layer-4	180 μ	Prepreg					A1	
	180 μ	Prepreg						
Layer-5	105 μ	Copper						A2
	360 μ	L-FR4						
Layer-99	105 μ	Copper		B				
	180 μ	Prepreg						
	180 μ	Prepreg			A1			
	105 μ	Copper						

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